



SI455W

High Tg, White Laminate for Chip LED Substrates

特点

- 高白度，高反射率
- 加热和 UV 光照后白度变化小
- 无卤环保材料

应用领域

- CHIP-LED
- CHIP-SMT
- LED COB 封装面板材料

FEATURES

- White LED with high reflectance of visible light
- Less discolouration after heat treatment and light irradiation
- Halogen free material

APPLICATIONS

- CHIP-LED
- CHIP-SMT
- LED COB Package Material

GENERAL PROPERTIES

Items	Condition	Unit	Property Data	
			Spec	Typical Value
Tg	DMA	°C	≥200	220
Flammability	C-48/23/50 and E-24/125	Rating	HB	HB
Volume Resistivity	After moisture resistance	MΩ-cm	≥10 ⁶	1.0E+10
	E-24/125		≥10 ³	4.5E+9
Surface Resistivity	After moisture resistance	MΩ	≥10 ⁴	8.5E+09
	E-24/125		≥10 ³	5.4E+08
Arc Resistance	D-48/50+D-0.5/23	S	≥60	142
Dielectric Breakdown	D-48/50+D-0.5/23	KV	≥40	45KV+NB
Whiteness	Heat condition	Internal Standard	≥80	81
	UV Irradiation	Internal Standard	≥80	82
Dielectric Factor	(1GHz)	C-24/23/50	-	5.5
Thermal Stress	288°C, solder dip	-	>10s No Delamination	>300s No Delamination
Peel Strength (HOz)	288°C/10s	N/mm	≥0.7	0.9
Young's modulus	LW	Gpa	≥26	28
	CW		≥25	27
Water Absorption	D-24/23	%	≤0.5	0.10
Z-axis CTE	Before Tg	PPM/°C	-	45
	After Tg	PPM/°C	-	220
	50-260°C	%	-	2.0
Td	5% Wt. loss	°C	≥360	390
T288	TMA	min	-	≥60

Specimen thickness: 0.4mm or 0.8mm. Test method is according to IPC TM-650